Vishay Siliconix

Automotive N-Channel 100 V (D-S) 175 °C MOSFET

Marking code: Q043

PRODUCT SUMMARY					
V _{DS} (V)	100				
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.022				
$R_{DS(on)}$ (Ω) at $V_{GS} = 4.5 \text{ V}$	0.025				
I _D (A)	18				
Configuration	Single				
Package	PowerPAK 1212-8W				

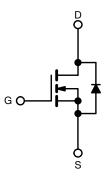
FEATURES

- TrenchFET® power MOSFET
- AEC-Q101 qualified
- 100 % R_q and UIS tested
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912



HALOGEN

FREE



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ($T_C = 25 ^{\circ}C$, unless	s otherwise noted	l)	
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage	V _{DS}	100		
Gate-source voltage	V_{GS}	± 20	V	
Continuous drain current ^a	T _C = 25 °C	1	18	
	T _C = 125 °C	l _D	18	
Continuous source current (diode conduction) a		I _S	18	Α
Pulsed drain current ^b		I _{DM}	72	
Single pulse avalanche current	. 0.1	I _{AS}	20.5	
Single pulse avalanche energy	L = 0.1 mH	E _{AS}	21	mJ
Maximum power dissipation ^b	T _C = 25 °C	P _D	62.5	W
	T _C = 125 °C		20	
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +175	00
Soldering recommendations (peak temperature) d, e		· · · · · ·	260	°C

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-ambient	PCB mount c	R _{thJA}	81	°C/W
Junction-to-case (drain)		R _{thJC}	2.4	C/VV

Notes

- a. Package limited
- b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %
- c. When mounted on 1" square PCB (FR4 material)
- d. See solder profile (www.vishay.com/doc?73257). The PowerPAK 1212-8W is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components

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PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static					l			
Drain-source breakdown voltage	V _{DS}	V _{GS}	= 0, I _D = 250 μA	100	-	-	V	
Gate-source threshold voltage	V _{GS(th)}	V _{DS} =	· V _{GS} , I _D = 250 μA	1.5	2.0	2.5	V	
Gate-source leakage	I _{GSS}	V _{DS} =	0 V, V _{GS} = ± 20 V	-	-	± 100	nA	
		$V_{GS} = 0 V$	V _{DS} = 100 V	-	-	1		
Zero gate voltage drain current	I_{DSS}	V _{GS} = 0 V	V _{DS} = 100 V, T _J = 125 °C	-	-	50	μΑ	
		V _{GS} = 0 V	V _{DS} = 100 V, T _J = 175 °C	-	-	150		
On-state drain current ^a	I _{D(on)}	V _{GS} = 10 V	$V_{DS} \ge 5 \text{ V}$	15	-	-	Α	
		V _{GS} = 10 V	I _D = 7 A	-	0.017	0.022		
During and the second and	Б	V _{GS} = 10 V	I _D = 7 A, T _J = 125 °C	-	-	0.041		
Drain-source on-state resistance a	R _{DS(on)}	V _{GS} = 10 V	I _D = 7 A, T _J = 175 °C	-	-	0.050	Ω	
		V _{GS} = 4.5 V	I _D = 5 A	-	0.020	0.025	1	
Forward transconductance b	9 _{fs}	V_{DS}	= 15 V, I _D = 7 A	-	47	-	S	
Dynamic ^b						l		
Input capacitance	C _{iss}			-	2068	2900		
Output capacitance	C _{oss}	$V_{GS} = 0 V$	V _{DS} = 25 V, f = 1 MHz	-	177	250	pF	
Reverse transfer capacitance	C _{rss}	-		-	13	20		
Total gate charge ^c	Qg			-	31	47		
Gate-source charge ^c	Q _{gs}	V _{GS} = 10 V	$V_{DS} = 50 \text{ V}, I_D = 2 \text{ A}$	-	6	-	nC	
Gate-drain charge ^c	Q _{gd}	-		-	5	-		
Gate resistance	R _g		f = 1 MHz	0.2	0.5	0.8	Ω	
Turn-on delay time ^c	t _{d(on)}			-	11	20		
Rise time ^c	t _r	V _{DD} =	= 50 V, R _I = 25 Ω	-	4	10		
Turn-off delay time ^c	t _{d(off)}	$I_D \cong 2 \text{ A}, \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \$	$I_{\rm GEN} = 10 \rm V, R_g = 1 \Omega$	-	25	40	ns	
Fall time ^c	t _f			-	9	15		
Source-Drain Diode Ratings and Charact	eristic ^b							
Pulsed current ^a	I _{SM}			-	-	72	Α	
Forward voltage	V _{SD}	I _F = 7 A, V _{GS} = 0 V		-	0.8	1.1	V	
Body diode reverse recovery time	t _{rr}			-	32	64	ns	
Body diode reverse recovery charge	Q _{rr}	- I _F = 2 A, di/dt = 100 A/μs		-	46	92	nC	
Reverse recovery fall time	t _a			-	26	-		
Reverse recovery rise time	t _b	1		-	6	-	ns	
Body diode peak reverse recovery current	I _{RM(REC)}			-	-3.4	-	Α	

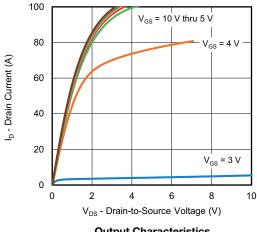
Notes

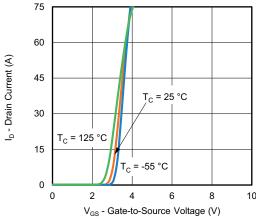
- a. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%$
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



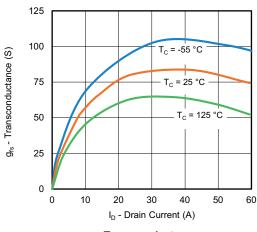
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)

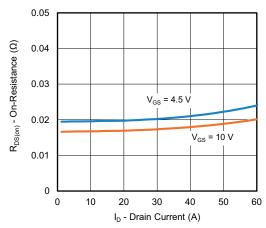






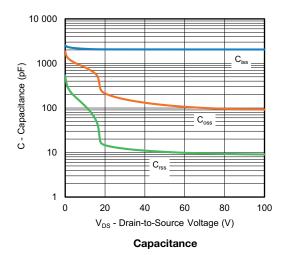


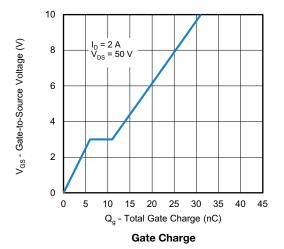




Transconductance

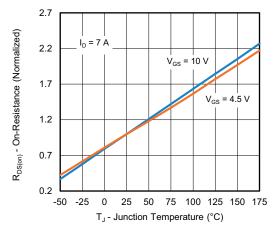
On-Resistance vs. Drain Current



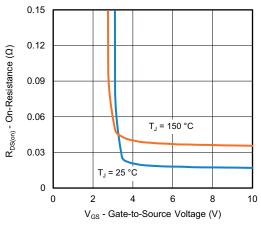




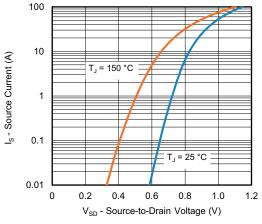
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



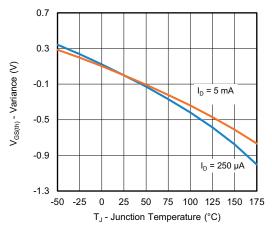
On-Resistance vs. Junction Temperature



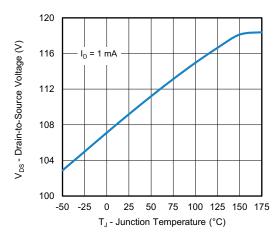
On-Resistance vs. Gate-to-Source Voltage



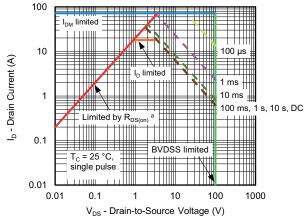
Source Drain Diode Forward Voltage



Threshold Voltage



Drain Source Breakdown vs. Junction Temperature



Safe Operating Area

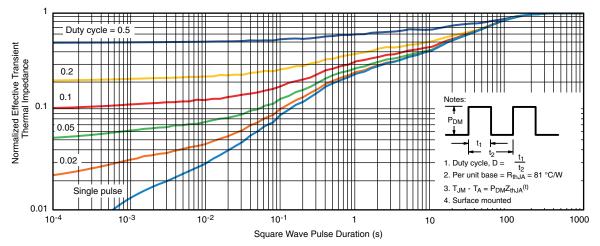
Note

a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

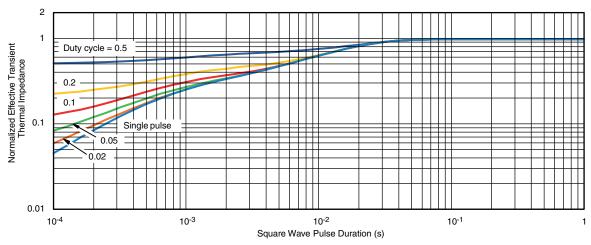
For technical questions, contact: automostech



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

Note

The characteristics shown in the two graphs

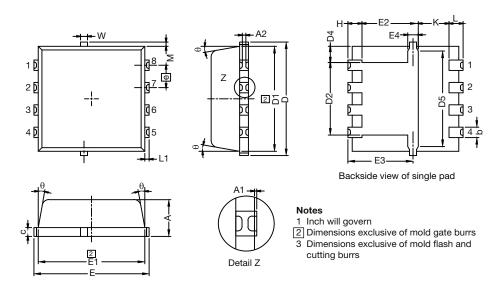
S20-0779-Rev. A, 19-Oct-2020

- Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
- Normalized Transient Thermal Impedance Junction-to-Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?78974.



PowerPAK® 1212-8W Case Outline



DIM.	MILLIMETERS			INCHES			
DINI.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
Α	0.97	1.04	1.12	0.038	0.041	0.044	
A1	0	-	0.05	0	-	0.002	
A2	0	-	0.13	0	-	0.005	
b	0.23	0.30	0.41	0.009	0.012	0.016	
С	0.23	0.28	0.33	0.009	0.011	0.013	
D	3.20	3.30	3.40	0.126	0.130	0.134	
D1	2.95	3.05	3.15	0.116	0.120	0.124	
D2	1.98	2.11	2.24	0.078	0.083	0.088	
D4		0.47 typ.		0.0185 typ.			
D5		2.3 typ.			0.090 typ.		
Е	3.20	3.30	3.40	0.126	0.130	0.134	
E1	2.95	3.05	3.15	0.116	0.120	0.124	
E2	1.47	1.60	1.73	0.058	0.063	0.068	
E3	1.75	1.85	1.98	0.069	0.073	0.078	
E4		0.34 typ.	0.013 typ.				
е		0.65 BSC.			0.026 BSC		
K		0.86 typ.		0.034 typ.			
Н	0.30	0.41	0.51	0.012	0.016	0.020	
L	0.30	0.43	0.56	0.012	0.017	0.022	
L1	0.06	0.13	0.20	0.002	0.005	0.008	
θ	0°	-	12°	0°	-	12°	
W	0.15	0.25	0.36	0.006	0.010	0.014	
М		0.125 typ.			0.005 typ.		

DWG: 6032



RECOMMENDED MINIMUM PADS FOR PowerPAK® 1212-8 Single



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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